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October 12, 1999

Assistant Commissioner for Patents U.S. Patent and Trademark Office Washington, D.C. 20231

Re:

Application of Gedney et al.

For:

IC CHIP ATTACHMENT

CH&G No.:

EN9-91-022R (21325/00276)

Dear Sir or Madam:

Enclosed please find the following:

- 1) Amendment (5 pages, in duiplicate);
- 2) Transmittal Sheet (1 pg. in duplicate);
- 3) Return Receipt Postcard

We do not believe there to be any additional fees required for this filing. However, if any fees are required or if the amount submitted with this application exceeds the required amount, please charge such fees or credit such overpayment to our Deposit Account No. 03-0172. A duplicate of this letter is enclosed for accounting purposes.

Very truly yours,

TECHNOLOGY CENTER 280(

Vames A. Rich

Enclosures

Certificate of Mailing

I hereby certify that this paper or fee is being deposited with the United States Postal Service, via First Class Mail to Addressee" under 37 CFR 1.10 on October 12, 1999 and is addressed to the Assistant Commissioner of Patents, Washington, D.C. 20231

Signer

{0276AMEN.DOC;1}

I hereby certify that this document is being deposited with the U.S. Postal Service via First Class Mail under 37 CFR 1.10 on October 12, 1999 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

VANES A. RICH

Signature

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applica	tion of Gedney et al.)		
Serial No:	09/004,524)	Art Unit: 2835	OCT 1 4 1999
Filed:	<i>J</i> anuary 8, 1998)		RADEMARIE
For:	IC CHIP ATTACHME) NT)	Examiner: Donald A. Span	rks
	S. Patent No. 5,483,421)	Attorney's Docket No: EN9-91-022R (21325/00276)	
Issued: January 9, 1996)	` c´	
		AMENDMENT	EIVE 8 1999 CENTER 2	TC F
Assistant Cor Washington,	nmissioner for Patents DC 20231		RECEIVED OCT 18 1999 FECHNOLOGY CENTER 2801	RECEIVED
Sir:			— #	首 写

In response to the Office Action of July 12, 1999, please amend this application as follows:

In the Specification

Please amend the paragraph at page 7, lines 7-18, which was amended in the Preliminary Amendment dated January 8, 1998, as follows:

In the present invention, the chip carrier 24 preferably is made of the same material as the circuit board, as will be described presently. If the chip carrier is not fashioned from the same material as the board, it must, in any event, have a similar coefficient of thermal expansion; i.e. the difference in the coefficient of thermal expansion between the carrier and the circuit board should not vary more than about 20%. The chip carrier and board are made from an organic dielectric material. In

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